



RC2 Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu).	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 50.41%	Copper (Cu)	7440-50-8	681.459	99.9793	503,966.9
	Phosphorus (P)	7723-14-0	0.007	0.0010	5.2
	Arsenic (As)	7440-38-2	0.007	0.0010	5.2
	Tin (Sn)	7440-31-5	0.007	0.0010	5.2
	Oxygen (O)	7782-44-7	0.003	0.0004	2.2
	Sulfur (S)	7704-34-9	0.082	0.0120	60.6
	Iron (Fe)	7439-89-6	0.004	0.0006	3.0
	Nickel (Ni)	7440-02-0	0.002	0.0003	1.5
	Bismuth (Bi)	7440-69-9	0.012	0.0018	8.9
	Antimony (Sb)	1309-64-4	0.012	0.0018	8.9
	Lead (Pb)	7439-92-1	0.003	0.0004	2.2
	Zinc (Zn)	7440-66-6	0.002	0.0003	1.5
	Total		681.60		
Solder Wafer 0.53%	Lead (Pb)	7439-92-1	6.66	92.50	4,925.3
	Tin (Sn)	7440-31-5	0.36	5.00	266.2
	Silver (Ag)	7440-22-4	0.18	2.50	133.1
	Total		7.20		
Chip 0.50%	Silicon (Si)	7440-21-3	6.49	95.40	4,797.6
	Lead (Pb)	7439-92-1	0.31	4.60	231.3
	Total		6.80		
Case 22.04%	Epoxy	38891-59-7	298.00	100.00	220,383.2
	Total		298.00		
Potting 26.11%		38891-59-7	353.00	100.00	261,058.0
	Total		353.00		
Plating 0.41%	Tin (Sn)	7440-31-5	5.59	100.00	4,134.0
	Total		5.59		
	Total mass (mg)		1,352.19		